

PRODUCT ADVANTAGE

High Reliability

100% Reworkable

Enhances Solder Joint
Strength 5-10X

Eliminate Underfill

Improve Process Yield

Eliminate Dendrite Formation

Reduce Cost

OUR THREE PILLARS

1. EXCEEDING PERFORMANCE
SPECIFICATIONS

2. MAXIMIZING PRODUCTIVITY

3. LOWERING PROCESS
COST

YINCAE Advanced Materials, LLC

19 Walker Way
Albany, NY 12205 USA
(518) 452-2880
www.yincae.com

Worldwide Service and Sales
Organization
info@yincae.com

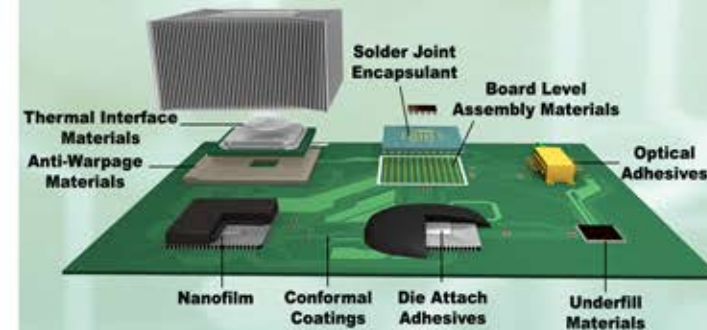
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YPB-002 (Version 1/2017)



INNOVATION AT ITS BEST



- THE GLOBAL LEADER
-Used in BILLIONS of Major Products by Industry Leaders
- UNLIMITED INDUSTRY APPLICATIONS
-Aeronautic, Astronautic, Automotive, Computers, Smartphones...
- HIGH CUSTOMER LOYALTY
-Customer Approved by Major Product Brands

SOLDER JOINT ENCAPSULANTS

*Preferred by global leaders in the
electronics manufacturing industry*

YINCAE® Solder Joint Encapsulant Family



Solder Joint Encapsulants

The YINCAE® Solder Joint Encapsulant Series is a family of microchip assembly and ball attachment adhesive products that are used to enhance solder joint reliability and eliminate solder joint cracking in CSP, BGA, flip chips and POP microchip applications.

Featured Products

BP 256: Lead free (SAC) ball bumping adhesives

SMT 256: Series of high temperature solder joint encapsulants available in different colors, storage conditions, and filler loads for dip, dispense, and print applications.

SMT 256EP: Combination of solder joint encapsulant and solder paste

SMT 266: Offers a lower viscosity for use in spray, jet, thermal compression bonding, and rework applications.

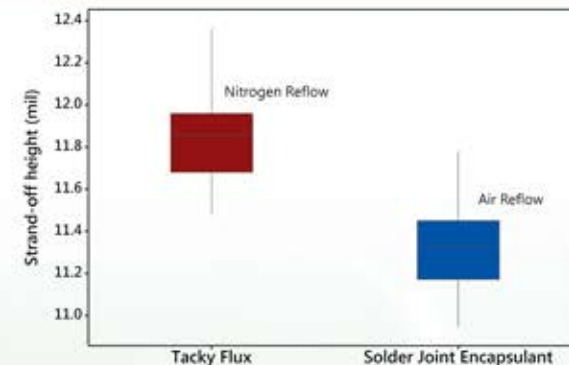
SMT 138: Series of SnBi based low temperature solder pastes available for dispense, print, and thermal compression bonding applications

Application of Solder Joint Encapsulant

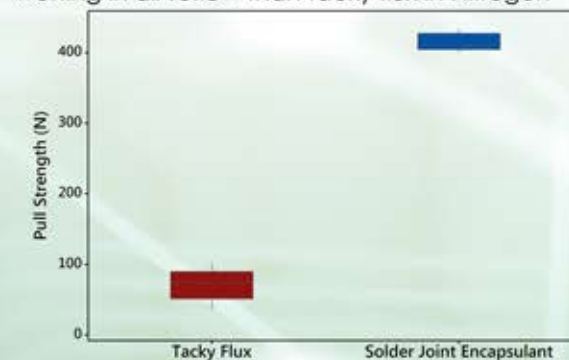


Microchip Assembling

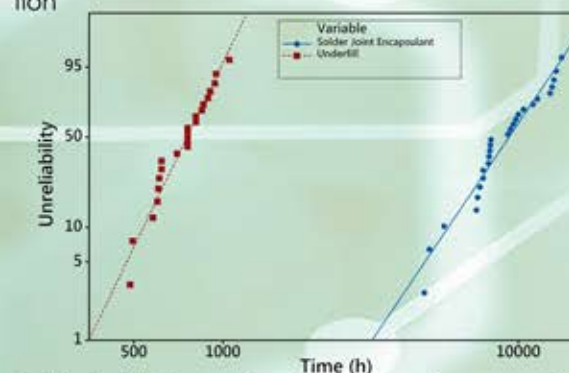
Product	Product Application	Reflow Peak Temp. (°C)
SMT 256	High temperature applications e.g. Pb free	230-260
SMT 256B	High temperature applications e.g. Pb free (Black)	230-260
SMT 256R	High temperature applications e.g. Pb free (Red)	230-260
SMT 256F40	High temperature applications - 40% filler load	230-260
SMT 256EP	High temperature solder paste	230-260
SMT 256EPT6	High temperature solder paste (Cu)	230-260
SMT 266	High temperature applications e.g. Pb free	230-260
SMT 266HR	Lead free & Sn/Pb applications; jetting process	230-260
BP 256	Ball attachment	230-260
BP 256R	Ball attachment (Red)	230-260
SMT 138P	Low temperature solder paste replacement - Printing	140-185
SMT 138E	Low temperature solder paste replacement - Dispense	140-185



Solder Joint Encapsulant provides better solder wetting in air reflow than tacky flux in Nitrogen



Solder Joint Encapsulant enhances solder joint strength 5x more than tacky flux with a smaller standard deviation



Solder Joint Encapsulant enhances thermocycling 10x, than tacky flux. (Thermal Cycling Conditions: 3AC305; I/O 1156; -55°C~150°C; 1h/cycle.)